

ABSTRACT OF THE DISCLOSURE

The present invention discloses a cooling structure for electronic devices which is characterized in that a plurality of electronic device accommodating boxes in which electronic devices are accommodated are accommodated in a casing in multiple stages, a vent portion which allows ventilation between the inside and the outside of the casing is formed in a ceiling of the casing, in a first accommodating portion for accommodating the first electronic device accommodating box which is defined at the stage close to the ceiling, a hollow duct having two opening faces is arranged, the first opening face faces the vent portion and the second opening face faces a second accommodating portion for accommodating the second electronic device accommodating box which is defined at the stage remote from the ceiling, air inside the second electronic device accommodating box which is accommodated in the second accommodating portion is discharged outside the casing from the vent portion through the inside of the duct, and air inside of the first electronic device accommodating box which is accommodated in the first accommodating portion is discharged to the outside of the casing from the vent portion along an outer wall surface of the duct.

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